

EQTG32D4EH-24.000M
[Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 12, 2019)
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**ITEM DESCRIPTION**

Temperature Compensated Quartz Crystal Clock Oscillators TCXO LVPECL (PECL) 2.5Vdc 6 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD) 24.000MHz -20°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	24.000MHz
Frequency Stability	±3.0ppm Maximum (Inclusive of Operating Temperature Range, at Vdd=2.5Vdc)
Frequency Stability vs. Frequency Tolerance	±1.5ppm Maximum (at 25°C ±2°C, at Vdd=2.5Vdc, Pre-Reflow)
Frequency Stability vs. Input Voltage	±0.2ppm Maximum (±5%)
Frequency Stability vs. Load	±0.2ppm Maximum (±2pF)
Frequency Stability vs. Reflow	±1.0ppm Maximum (at 25°C, 24 hours after reflow, 1 time)
Frequency Stability vs. Aging	±1ppm/Year Maximum (at 25°C)
Operating Temperature Range	-20°C to +70°C
Supply Voltage	2.5Vdc ±5%
Input Current	75mA Maximum
Output Voltage Logic High (Voh)	Vdd-1.025Vdc Minimum, 1.6Vdc Typical, Vdd-0.6Vdc Maximum
Output Voltage Logic Low (Vol)	Vdd-1.85Vdc Minimum, 0.8Vdc Typical, Vdd-1.62Vdc Maximum
Rise/Fall Time	300pSec Maximum (Measured at 10% to 90% of Waveform)
Duty Cycle	50 ±5(%) (Measured at 50% of Waveform)
Load Drive Capability	50 Ohms into Vdd-2Vdc
Output Logic Type	LVPECL
Phase Noise	-64dBc/Hz at 10Hz offset; -96dBc/Hz at 100Hz offset; -124dBc/Hz at 1kHz offset; -131dBc/Hz at 10kHz offset; -132dBc/Hz at 100kHz offset; -149dBc/Hz at 1MHz offset; -157dBc/Hz at 10MHz offset; -159dBc/Hz at 20MHz offset (All Values are Typical)
Output Control Function	Output Enable (OE)
Output Control Input Voltage Logic High (Vih)	90% of Vdd Minimum or No Connect to Enable Output and Complementary Output
Output Control Input Voltage Logic Low (Vil)	10% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)
Output Enable Time	100nSec Maximum
Output Disable Time	50nSec Maximum
Output Enable Current	15mA Maximum (Without Load (Pin 2 = Ground))
RMS Phase Jitter	1.5pSec Maximum (Fj=12kHz to 20MHz (Random))
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	2pSec Typical
Period Jitter (RMS)	3pSec Maximum
Period Jitter (pk-pk)	30pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

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ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Do Not Connect
2	Output Enable (OE)
3	Case/Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	E24.000 E=Ecliptek Designator
2	XXXXX XXXXX=Ecliptek Manufacturing Identifier

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

Suggested Solder Pad Layout

All Dimensions in Millimeters

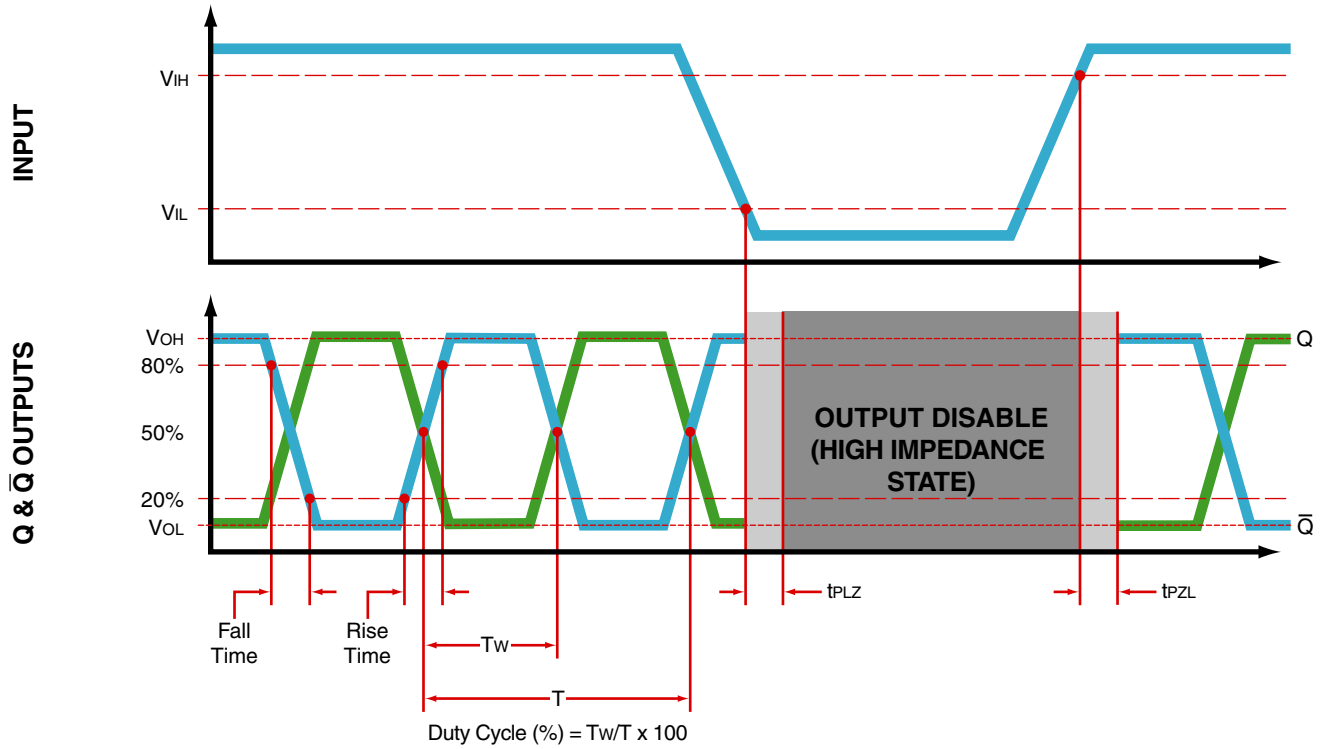


All Tolerances are ±0.1

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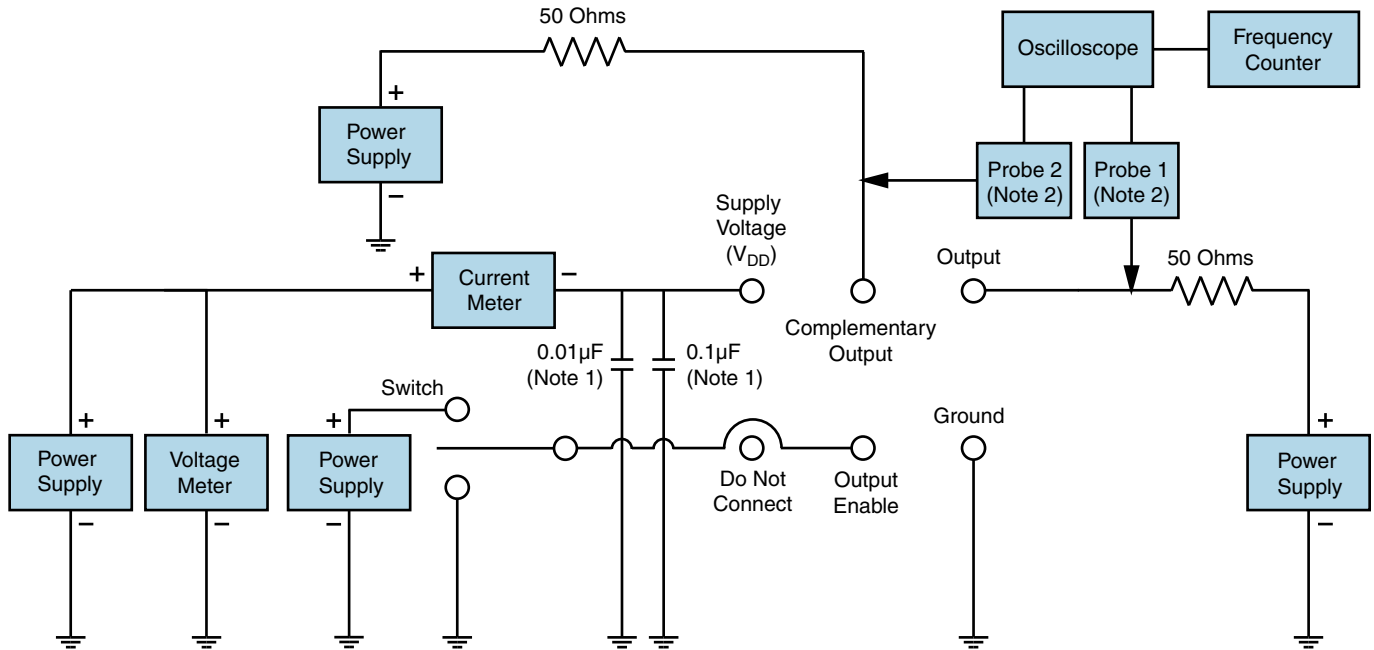
OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for PECL Output



Note 1: An external 0.01 μF ceramic bypass capacitor in parallel with a 0.1 μF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

$T_s \text{ MAX}$ to T_L (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum ($T_s \text{ MIN}$)	150°C
- Temperature Typical ($T_s \text{ TYP}$)	175°C
- Temperature Maximum ($T_s \text{ MAX}$)	200°C
- Time ($t_s \text{ MIN}$)	60 - 180 Seconds
Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature ($T_P \text{ Target}$)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_s MAX to T_L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	N/A
- Temperature Typical (T_s TYP)	150°C
- Temperature Maximum (T_s MAX)	N/A
- Time (t_s MIN)	60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature (T_P Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (t_p)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)